



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  * : Required Field

<b>Supplier Information</b>			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-12-22
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Giovanni Giacopello	<b>Representative Title</b>	ADG MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STD13N60DM2	TXDP*FQ63B62	A	3068	2016-12-22
Amount	UoM	Unit type	ST ECOPACK Grade	
330.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	6.5-6.1-2.3	3	GULL WING	
Comment	TO 252 DPAK			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 5th August 2016			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.14	Die / Leadframe	433
Lead	6.73	Soft solder	20379

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	TXDP*FQ63862		330.0000			
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	5.691	mg	supplier	die	Silicon (Si)	7440-21-3		5.379	mg	945177	16300
				supplier	metallization	Aluminium (Al)	7429-90-5		0.150	mg	26357	455
				supplier	Passivation	Silicon Nitride	12033-89-5		0.036	mg	6326	109
				supplier	Passivation	Silicon Oxide	7631-86-9		0.053	mg	9313	161
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.004	mg	702	12
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.051	mg	8962	155
Leadframe	Copper & its alloys	165.042	mg	supplier	back side metallization	Silver (Ag)	7440-22-4		0.018	mg	3163	55
				supplier	alloy	Copper (Cu)	7440-50-8		164.151	mg	994601	497427
				supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		0.330	mg	1999	1000
				supplier	alloy	Cobalt (Co)	7440-48-4		0.462	mg	2799	1400
				supplier	metallization	Nickel (Ni)	7440-02-0		0.092	mg	557	279
				supplier	metallization	Phosphorus (P)	12185-10-3		0.007	mg	44	21
Soft solder	Solder	7.042	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	6.725	mg	954984	20379
				supplier	solder	Silver (Ag)	7440-22-4		0.176	mg	24993	533
				supplier	solder	Tin (Sn)	7440-31-5		0.141	mg	20023	427
Bonding wires	Other inorganic materials	0.458	mg	supplier	wire	Aluminium (Al)	7429-90-5		0.456	mg	995633	1382
				supplier	wire	Magnesium (Mg)	7439-95-4		0.002	mg	4367	6
				supplier	mold compound	Silica, vitreous	60676-86-0		131.881	mg	874995	399639
Encapsulation	Other Organic Materials	150.722	mg	supplier	mold compound	Tetramethyl-biphenyl-diyl-bis oxymethylene-b	EC 413-900-7		6.029	mg	40001	18270
				supplier	mold compound	Epoxy Resin	25068-38-6		4.522	mg	30002	13703
				supplier	mold compound	phenol resin	29690-82-2		7.536	mg	49999	22836
				supplier	mold compound	Carbon black	1333-86-4		0.754	mg	5003	2285
Connections coating	Solder	1.045	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.045	mg	1000000	3167